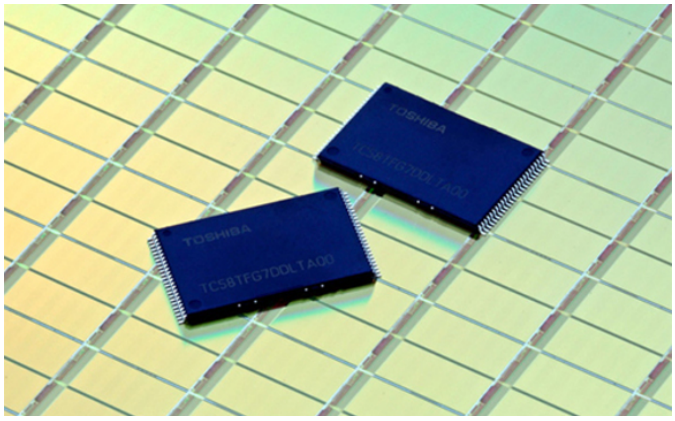


Western Digital (WD) presents the next generation of 3D NAND flash-- BiCS3, featuring 64 layers of vertical storage capability on a single 3-bits-per-cell chip, making it the smallest from the company.

Co-developed with Toshiba, BiCS3 will initially be deployed in 256 gigabit capacity before availability in a range of capacities reaching up to half a terabit on a single chip. It will run alongside the current range of BiCS2 3D NAND products.

"BiCS3 will feature the use of three-bits-per-cell technology along with advances in high aspect ratio semiconductor processing to deliver higher capacity, superior performance and reliability at an attractive cost," WD says. "Together with BiCS2, our 3D NAND portfolio has broadened significantly, enhancing our ability to address a full spectrum of customer applications in retail, mobile and data centre."

Pilot production of has already started at the WD Yokkaichi, Japan facility. Some limited consumer products are promised to hit the market by Q4 2016 before "meaningful production volumes" start on H1 2017.

Go WD Announces World's First 64 Layer 3D NAND Technology